

Specifications

Systems

System controller	Integrated controller with 8 Core Intel Xeon processors
Operating system	Windows 8 (64 bits)

Test Development Environment

User interface	Microsoft Windows based software solution with easy-to-use GUI and password-protected user levels
Off-line test development software	Optional for off-line PC
Test sight developer	Optional software available to translate CAD data to ViTroX's format
Typical test development time	4 hours to 1.5 days to convert raw CAD file and develop application

Line Integration

Transport heights	865mm-1025mm
Line communication standard	SMEMA
Barcode readers	Compatible with most industry standard barcode readers

Performance Parameters *

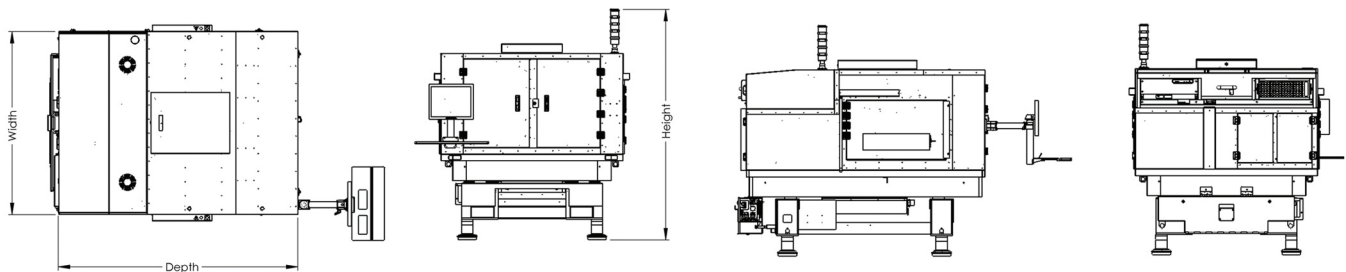
Total panel test cycle time	51.68cm ² /sec (8 in ² /sec) at 19um
Typical Image Acquisition Rate	500 - 1000 ppm
False call rates	
Minimum features detection capability	
Joint pitch ¹	0.3 mm and up
Short width ²	0.045 mm
Solder thickness	0.0127 mm

Allowable panel characteristics **

Maximum Panel size	482mm X 610mm (19"x24")
Minimum Panel size	76mm X 76mm (3" x 3")
Maximum panel inspectable area	474mm X 610mm (18.7" X 24")
Maximum Panel thickness	7mm(276mils)
Minimum Panel thickness	0.5mm (20mils)
Panel warp	Downside<3mm,upside< 1.5mm (PSP)
Maximum Panel weight	4.5kg
Minimum Panel weight	0.03kg
Board top clearance	50mm @ 23um resolution, 38mm @ 19um resolution 11mm @ 11um resolution * Calculated from board top surface
Board bottom clearance	70mm
Panel edge clearance	3.0mm
Panel width tolerance	+/-0.7mm
System resolution	11um, 19um, 23um
100% Press-fit testability	Yes (With PSP2 feature)
Maximum acceptable panel temperatures	40 Deg C

Power and environmental

Voltage requirement	200 - 240 VAC three phase; 380 - 415 VAC three phase wye (± 5) (50Hz or 60 Hz)
Air requirement	552 kPa (80 psi) compressed air
System footprint (Width X Depth X Height)	1566mm X 2145mm X 1972mm
Total system weight	~3500kg



*** Note :**

1. Assuming pad width is 50% of pitch.
2. The reported values for minimum feature detection assume that the feature is in a single plane of focus and that there are no X-ray absorbers in the X-ray path or in the immediate area of the feature other than those found in a typical multi-layer printed circuit board.

**** Note :**

1. Panels are handled on width edges. Panels with edge cut outs may require the use of a carrier.
2. Maximum panel size dimensions and weight must include carrier if applicable.
3. Smaller panels are possible with the use of panel carriers.
4. With panels of this thickness, imaging results can be affected by PCBA layout.
5. Measured from the bottom of the panel including a maximum warp.